



HPH2369

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HPH2369 is designed for general purpose switching and amplifier applications.

Features

- Low Collector Saturation Voltage
- High speed switching Transistor

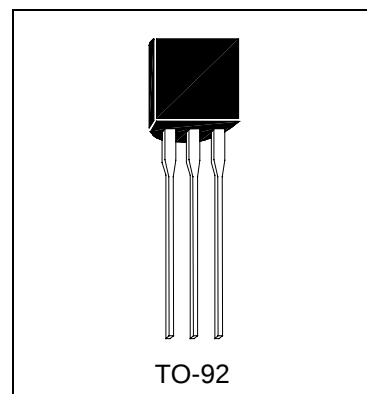
Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage 40 V
VCES Collector to Emitter Voltage 40 V
VCEO Collector to Emitter Voltage 15 V
VEBO Emitter to Base Voltage 4.5 V
IC Collector Current 500 mA

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	40	-	-	V	IC=100uA, IE=0
BVCEO	15	-	-	V	IC=10mA, IB=0
BVCES	40	-	-	V	IC=10uA, VBE=0
BVEBO	4.5	-	-	V	IE=10uA, IC=0
ICBO	-	-	400	nA	VCB=20V, IE=0
ICES	-	-	300	nA	VCE=25V, VBE=0
IEBO	-	-	100	nA	VEB=2V, IC=0
*VCE(sat)1	-	-	250	mV	IC=10mA, IB=1mA
*VCE(sat)2	-	-	300	mV	IC=10mA, IB=0.3mA
*VCE(sat)3	-	-	600	mV	IC=100mA, IB=10mA
*VBE(sat)1	700	-	850	mV	IC=10mA, IB=1mA
*VBE(sat)2	-	-	1.5	V	IC=100mA, IB=1mA
*hFE1	40	80	120		IC=10mA, VCE=1V
*hFE2	20	-	-		IC=100mA, VCE=2V
fT	500	-	-	MHz	IC=10mA, VCE=10V, f=100MHZ
Cob	-	-	4	pF	VCB=5V, f=1MHz, IE=0

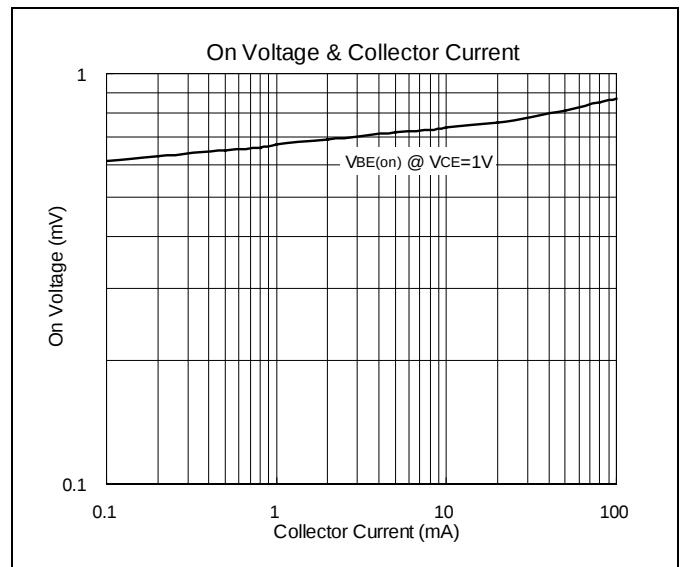
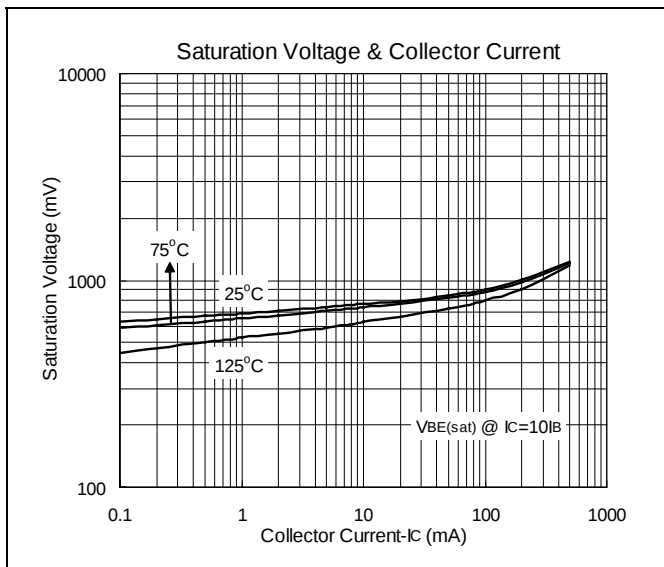
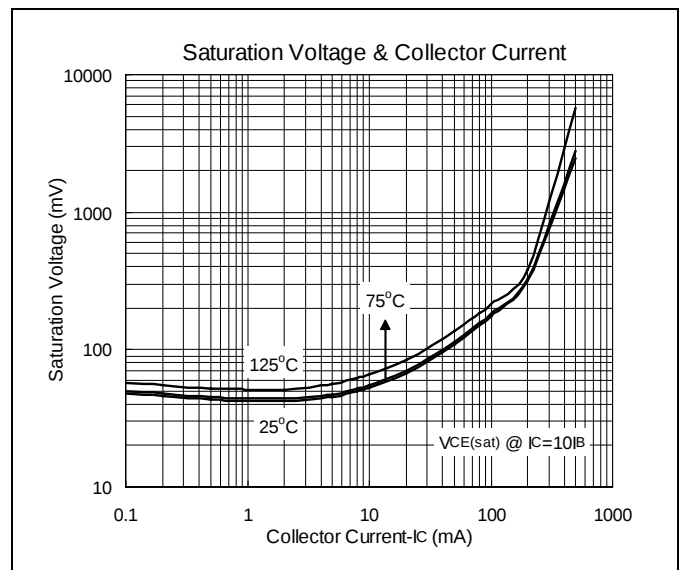
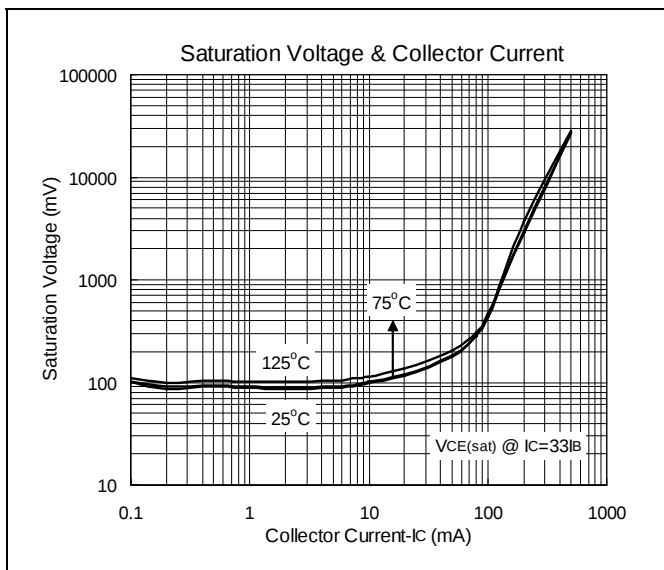
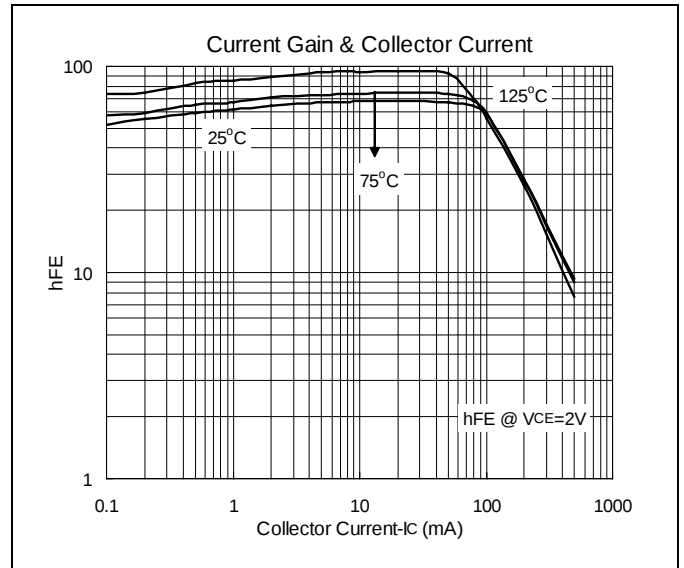
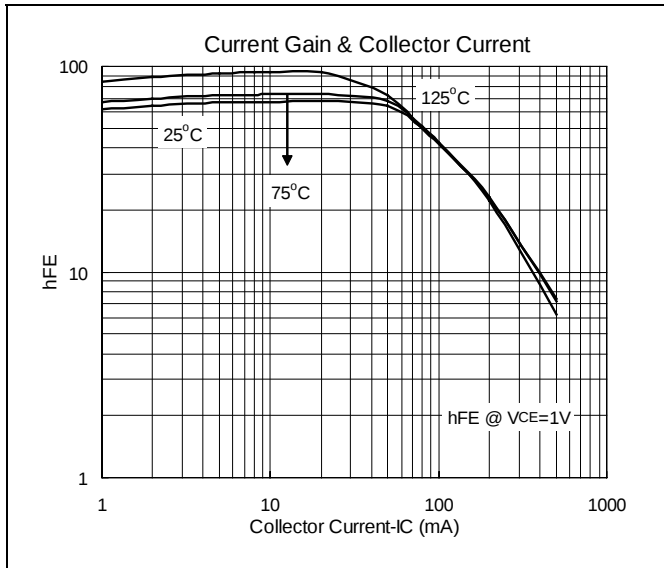
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

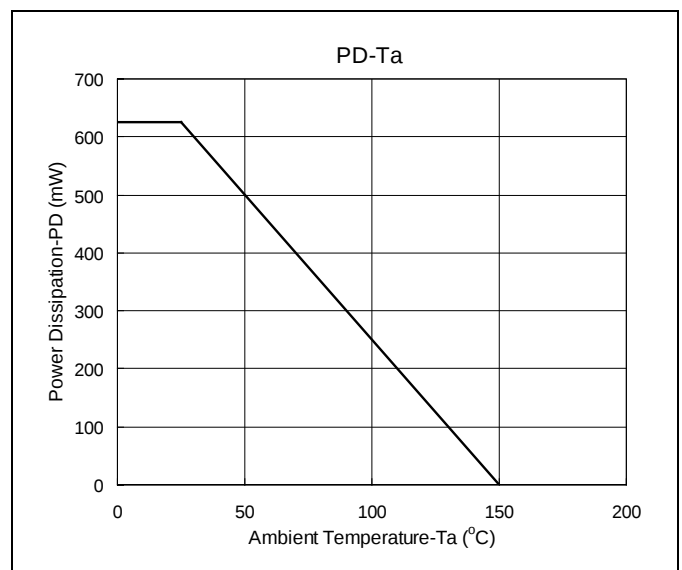
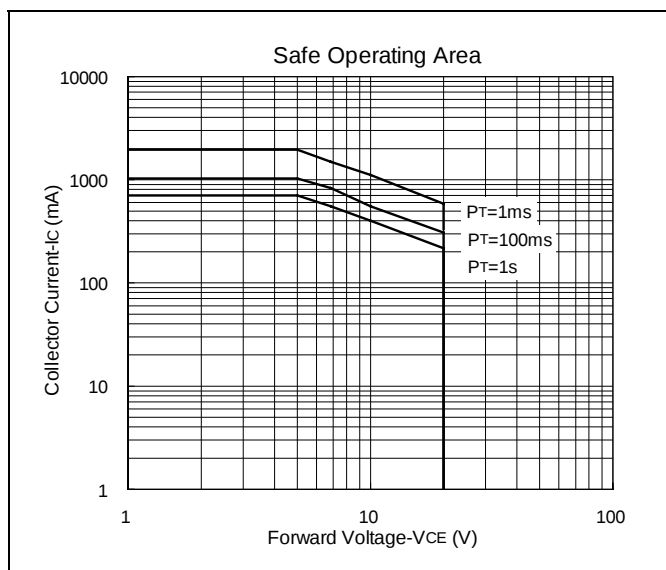
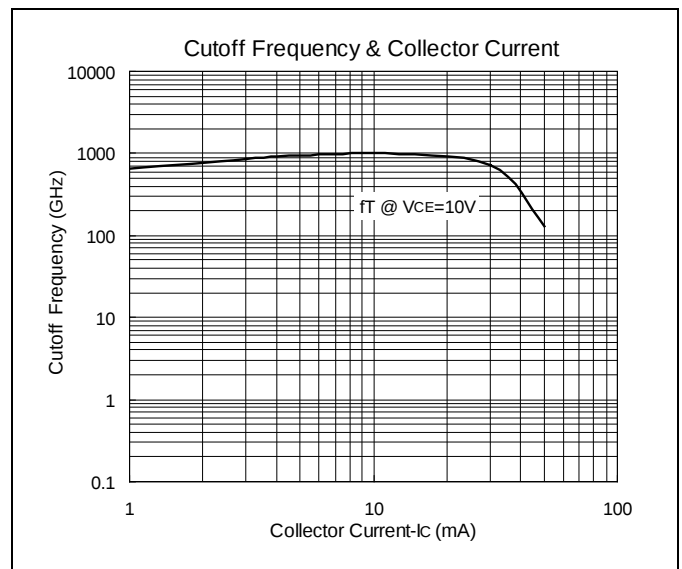
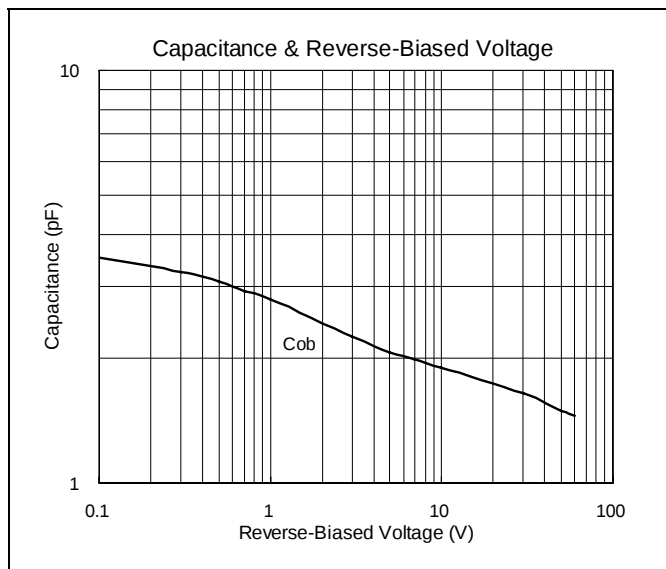


TO-92



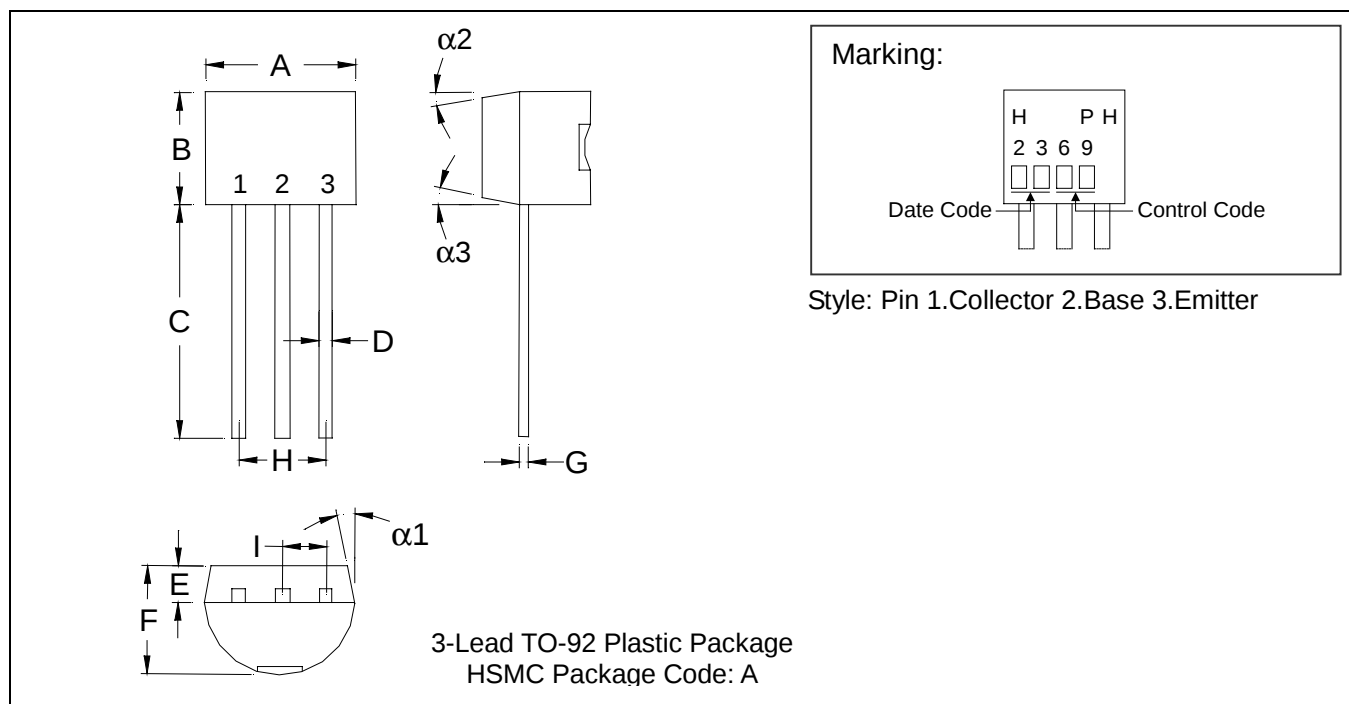
Characteristics Curve







TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
2.Controlling dimension: millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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